



Winner of the
productronica
innovation award 2019

Semiconductor cluster – ASM AMICRA



CoS Bonder

The ASMPT Group's AMICRA CoS system is a very flexible and powerful die bonder for chip-on-submount applications.

The CoS system combines the extremely precise AMICRA dynamic alignment concept with an innovative motion sequence designed to increase productivity. The CoS system has a rotating bonding station with two separate bonding positions and an innovative multi-pick head for accelerated supplying and unloading of substrates. Eutectic bonding is carried out with an innovative and very powerful

ceramic heater or alternatively with a laser, and a stamping / adhesive unit is also offered for this.

The result of the development work is a die bonder, which is as precise as it is productive, for one or more chips on isolated substrates. The innovative AMICRA CoS solution therefore fulfills the rapidly expanding packaging requirements of the photonics, 5G, data communication, LiDAR 3D sensor technology and augmented reality sectors.



Johann Weinhändler, Managing Director, ASM AMICRA Microtechnologies GmbH:

“The development of our new chip-on-submount die bonder is based heavily on the development-related synergies available to us on account of our successful integration within the ASMPT Group. The result is a CoS die bonder which achieves optimum bonding precision on account of the AMICRA dynamic alignment concept and, thanks to the ASMPT assemblies, also increases productivity. We are proud to receive the Messe München productronica award which will also spur the entire ASMPT team on to support the rapid developments in the

advanced packaging sector with innovative, powerful technologies and products.”

About ASM AMICRA Microtechnologies GmbH

ASM AMICRA Microtechnologies' core business is the development, production and sale of high-precision production systems for automated microchip assembly in the electronics and semiconductor industry. Boasting submicron placement accuracy ($\pm 0.3\mu\text{m}@3\text{sigma}$), ASM AMICRA solutions pave the way for innovative applications in the photonics, data communication, optical device packaging and advanced packaging sectors.

Founded in 2001, ASM AMICRA Microtechnologies GmbH now employs more than 130 staff at its headquarters in Regensburg from over 10 different countries.

The company has been part of ASM Pacific Technology's Back-end Equipment business since 2018 and also benefits from the resources and technological and economic synergies of the world's largest equipment manufacturer for the electronics industry.

For more information, visit www.amicra.asmpt.com

About ASM Pacific Technology Limited (ASMPT)

Enabling the digital world: as the only company of its kind anywhere in the world, ASMPT has been supplying best-in-class equipment for all levels of the electronics industry through its three business segments, namely Back-end Equipment (chip assembly), Materials, and SMT Solutions, since 1975.

ASMPT (HKEX stock code: 0522), headquartered in Singapore, is a global technology and market leader. The level and extent of its process expertise are unrivaled by any other manufacturer. The company's continuous investments in research and development also help ensure that it provides its customers with innovative and cost-effective solutions and systems which they can use in turn to increase productivity, reliability and quality.

For more information on ASMPT, visit www.asmpacific.com.

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